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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL. NUM 10081796	FILING DATE 02/22/2002	CLASS 204	SUBCLASS 192.12	GAU 1753	EXAMINER McDonald
**APPLICANTS: Denning Dean; Garcia Sam; Smith Bradley; Loop Daniel; Hamilton Gregory; Islam Md.; Anthony Brian;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A DIV OF 09/261,879 03/02/1999					
** FOREIGN APPLICATIONS VERIFIED: <i>none</i>					
PG-PUB		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no Verified and Acknowledged Examiners's initials <i>pm</i>				ATTORNEY DOCKET NO SC91135A D01	
TITLE : Method for forming a barrier layer for use in a copper interconnect					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)					
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NOTICE OF ALLOWANCE MAILED		Assistant Examiner		CLAIMS ALLOWED	
				Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner		DRAWING	
Amount Due	Date Paid			Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE		Application Examiner	
		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

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